

SANYO Semiconductors DATA SHEET

An ON Semiconductor Company

N-Channel Silicon MOSFET

ATP613 — General-Purpose Switching Device Applications

Features

- Reverse recovery time t_{rr}=60ns(typ.)
- Input Capacitance Ciss=350pF(typ.)
- · Halogen free compliance

- ON-resistance RDS(on)=1.55 Ω (typ.)
- · 10V drive

Specifications

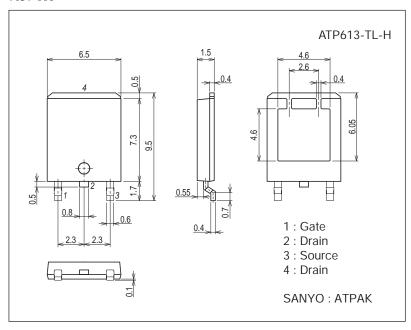
Absolute Maximum Ratings at Ta=25°C

Parameter	Symbol	Conditions	Ratings	Unit
Drain-to-Source Voltage	V _{DSS}		500	V
Gate-to-Source Voltage	VGSS		±30	V
Drain Current (DC)	ID		5.5	Α
Drain Current (Pulse)	IDP	PW≤10μs, duty cycle≤1%	19	Α
Source-to-Drain Diode Forward Current (DC)	IS		5.5	Α
Source-to-Drain Diode Forward Current (Pulse)	ISP	PW≤10μs, duty cycle≤1%	19	Α
Allowable Power Dissipation	PD	Tc=25°C	70	W
Channel Temperature	Tch		150	°C
Storage Temperature	Tstg		-55 to +150	°C
Avalanche Energy (Single Pulse) *1	EAS		93	mJ
Avalanche Current *2	IAV		5.5	Α

Note: *1 VDD=99V, L=5mH, IAV=5.5A (Fig.1)

Package Dimensions

unit : mm (typ) 7057-001



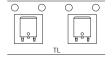
Product & Package Information

• Package : ATPAK

• JEITA, JEDEC :-

• Minimum Packing Quantity : 3,000 pcs./reel

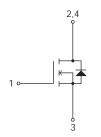
Packing Type: TL



Marking



Electrical Connection



^{*2} L≤5mH, Single pulse

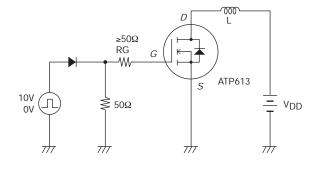
Electrical Characteristics at Ta=25°C

Parameter	Cumbal	Conditions	Ratings			Unit	
Parameter	Symbol	Conditions	min	typ	max	Unit	
Drain-to-Source Breakdown Voltage	V(BR)DSS	ID=10mA, VGS=0V	500			V	
Zero-Gate Voltage Drain Current	IDSS	V _{DS} =400V, V _{GS} =0V			100	μΑ	
Gate-to-Source Leakage Current	IGSS	V _{GS} =±30V, V _{DS} =0V			±100	nA	
Cutoff Voltage	VGS(off)	V _{DS} =10V, I _D =1mA	3		5	V	
Forward Transfer Admittance	yfs	VDS=10V, ID=2.75A	1.5	2.9		S	
Static Drain-to-Source On-State Resistance	R _{DS} (on)	I _D =2.75A, V _G S=10V		1.55	2.0	Ω	
Input Capacitance	Ciss			350		pF	
Output Capacitance	Coss	V _{DS} =30V, f=1MHz		68		pF	
Reverse Transfer Capacitance	Crss			15		pF	
Turn-ON Delay Time	t _d (on)			14.2		ns	
Rise Time	t _r	Soo Fig 2		46		ns	
Turn-OFF Delay Time	t _d (off)	See Fig.2		37.6		ns	
Fall Time	t _f			20.4		ns	
Total Gate Charge	Qg			13.8		nC	
Gate-to-Source Charge	Qgs	V _{DS} =200V, V _{GS} =10V, I _D =5.5A		3.2		nC	
Gate-to-Drain "Miller" Charge	Qgd			7.6		nC	
Diode Forward Voltage	V _{SD}	I _S =5.5A, V _{GS} =0V		1.1	1.5	V	
Reverse Recovery Time	t _{rr}	See Fig.3		60		ns	
Reverse Recovery Charge	Q _{rr}	IS=5.5A, VGS=0V, di/dt=100A/μs		120		nC	

Fig.1 Unclamped Inductive Switching Test Circuit

V_{DD}=200V VIN

Fig.2 Switching Time Test Circuit



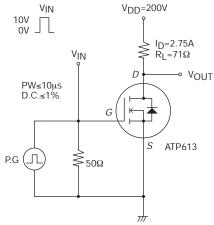
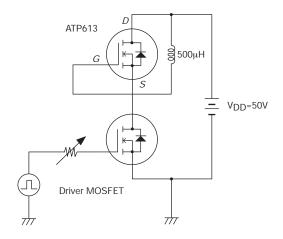
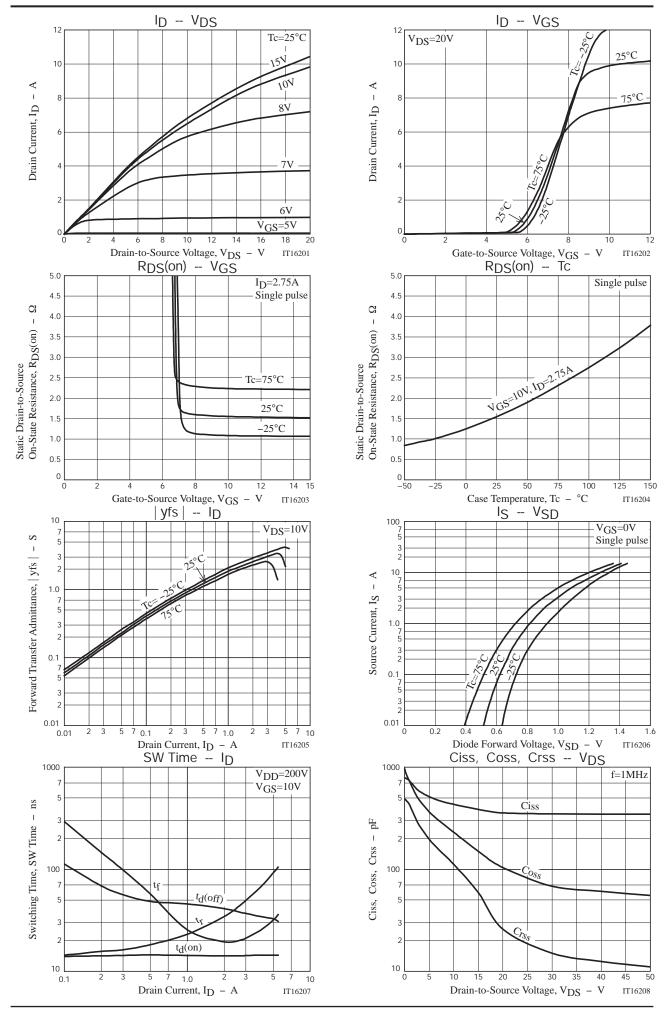


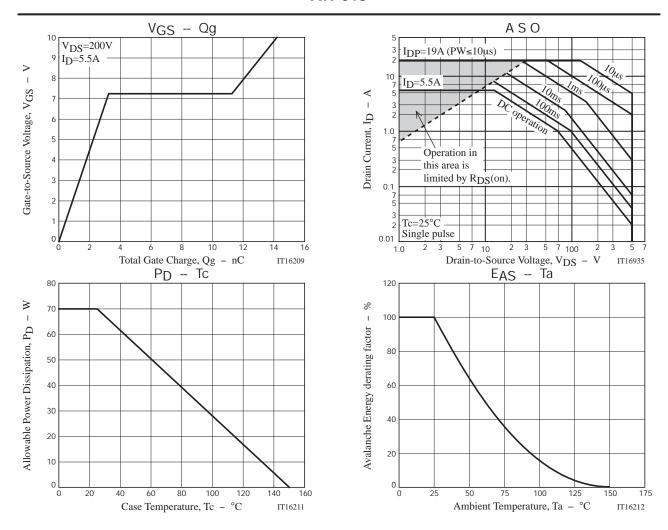
Fig.3 Reverse Recovery Time Test Circuit



Ordering Information

Device	Package	Shipping	memo	
ATP613-TL-H	ATP613-TL-H ATPAK		Pb Free and Halogen Free	



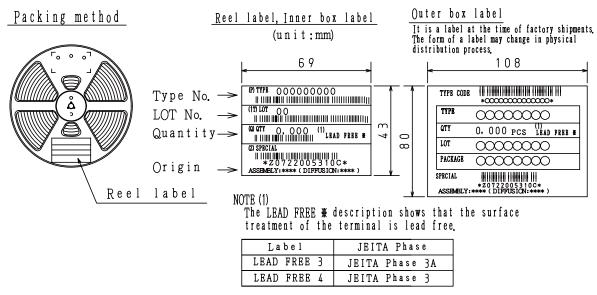


Taping Specification

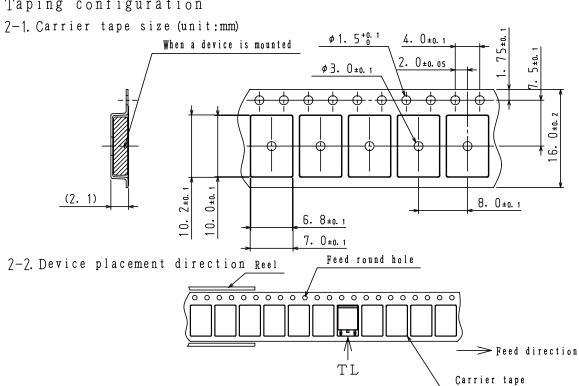
ATP613-TL-H

1. Packing Format (TL)

Package Name Carrier Tape Type		Maximum Number of devices contained (pcs)			Packing format		
		Reel	Inner box	Outer box	INNER BOX SD-C-18	OUTER BOX SD-A-18	
		03,000	15,000	1 reels contained	5 inner boxes contained		
ATPAK	AK ATP 3,000			Dimensions:mm (external)	Dimensions:mm (external)		
					340×340×28	355×355×165	



7. Taping configuration



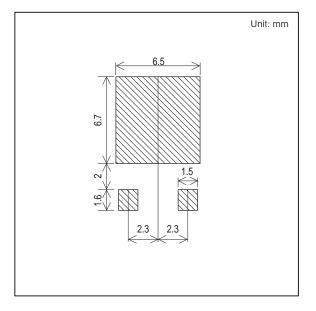
The one erectrode terminals on feed hole side····TL

Outline Drawing

ATP613-TL-H

Mass (g) Unit 0.266 mm 6.540.15 4 4 5.540.15 6.540.

Land Pattern Example



Note on usage: Since the ATP613 is a MOSFET product, please avoid using this device in the vicinity of highly charged objects.

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